

## Peelable Solder Mask

This PCB solder mask is a synthetic latex product for the temporary masking of circuit areas and contacts against solder, rosin and cleaning fluids. It provides effective protection for contacts, gold fingers and printed circuit card edges, and can easily be peeled off once the wave soldering process is complete, and after any subsequently applied conformal coating is sufficiently dry.

Our peelable solder mask can be applied by hand or by template screening, but not by silk screening. It can also be applied using robotic or pneumatic systems.



## Features & Benefits

- Dissolves light oils and residues on electronic devices and equipment
- Combines polar and non-polar solvent cleaning action
- Zero residue
- Safe on plastics and methanol-free
- Quick-drying relative to water
- Variable valve allows user to control the rate of flow
- CARB compliant
- Suitable for use in food facilities as a Non-Food Chemical—Canadian and NFS recognition letters available on request

## Available Packaging

| Cat. No.  | Packaging | Net Vol. | Net Wt. |
|-----------|-----------|----------|---------|
| 862-250ML | Tube      | 250 mL   | 250 g   |

## Contact Information

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Burlington, Ontario, Canada L7L 5R6

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## Cured Properties

|                                 |                  |
|---------------------------------|------------------|
| Aqueous Solubility              | Insoluble        |
| Solvent Solubility              | Low or insoluble |
| Weight Loss @ 200 °C, 10 °C/min | 2.0 %            |
| @ 225 °C, 10 °C/min             | 4.3 %            |
| @ 250 °C, 10 °C/min             | 7.7 %            |
| Wave Solder Tolerant            | Yes              |
| Peelability                     | Excellent        |
| Service Temperature Range       | -50–150 °C       |

## Usage Parameters

|                               |                       |
|-------------------------------|-----------------------|
| Cure Time                     | 60 min @ 22 °C        |
|                               | 30 min @ 65 °C        |
|                               | 20 min @ 80 °C        |
| Max. Intermittent Temperature | 250 °C                |
| Recommended Thickness         | 500–760 µm            |
| Theoretical Coverage @ 500 µm | 2 400 cm <sup>2</sup> |

## Uncured Properties

|                   |           |
|-------------------|-----------|
| Viscosity @ 25 °C | 29 000 cP |
| Density           | 1.0 g/mL  |
| Solids Content    | 50 %      |

## Application Instructions

Read the product SDS and Application Guide for more detailed instructions before using this product (downloadable at [www.mgchemicals.com](http://www.mgchemicals.com)).

## Recommended Preparation

Clean the substrate with Isopropyl Alcohol, MG #824, so the surface is free of oils, dust, and other residues.

1. Apply 500 to 760  $\mu\text{m}$  to the desired area.
2. For better coverage control, use a stencil.
3. If product is too thick, thin it with deionized (D.I.) water.
- 4 Do not remove mask until product becomes completely translucent.

## Cure Instructions

Allow to cure at room temperature for 1 hour, or cure in an oven at one of these time/temperature options:

- 30 min @ 65 °C
- 20 min @ 80 °C

## Storage and Handling

Store between 16 and 27 °C in a dry area, away from sunlight. To maximize shelf life, recap product firmly when not in use.

## Disclaimer

This information is believed to be accurate. It is intended for professional end-users who have the skills required to evaluate and use the data properly. M.G. Chemicals Ltd. does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

